

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants : Wendy Lee Wilkins  
Title : Die-First Multi-Chip Modules and Methods of , , ,  
Application No. : 10/724,981  
Confirmation No. : 1888  
Filing Date : 11/30/03  
Examiner : Michael A. Brown  
Group Art Unit : 3772  
Attorney Docket : 783403605015

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

In response to the Office Action mailed 12/28/07, please amend the application as follows.

Any fee due for this submission may be charged to the Jones Day Deposit Account No. 501432, reference 783403605015.